

IN THE CLAIMS

1-9. (Cancelled)

10. (Previously and Presently Amended) A method for establishing product integrity after shipment from one location to another location, comprising the step of:

attaching one or more smart sensors directly to the product,

monitoring environmental conditions of the product via the sensors and during shipment,
wirelessly communicating the conditions from the sensors to a receiver at the
second location, and

communicating the conditions from the receiver to a third location.

11. (Original) A method of claim 10, wherein the step of communicating the conditions to the first location comprises communicating the conditions through the Internet.

12. (Original) A method of claim 10, further comprising interrogating, with the receiver, the sensors at the second location, and before the step of wirelessly communicating.

13. (Original) A method of claim 10, wherein the step of monitoring environmental conditions comprises detecting acceleration at at least one of the sensors.

14. (Original) A method of claim 10, the step of attaching comprising attaching an accelerometer to the product, and further comprising detecting free fall to determine a drop distance of the product.

15. (Original) A method of claim 10, the step of monitoring environmental conditions comprising monitoring temperature relative to preset temperature guidelines of the product.

16. (Previously Presented) A system for determining integrity of a product through shipment, comprising:

one or more smart sensors for attachment to the product and an interrogating device, the sensors monitoring environmental conditions of the product during shipment and wirelessly

communicating data about the conditions to the interrogating device during or after shipment, the interrogating device communicating the conditions over a network.

17. (Previously Presented) The system of claim 16, the network comprising the Internet.
18. (Previously Presented) The system of claim 16, the interrogating device comprising hand-held electronics.
19. (Previously Presented) The system of claim 16, wherein the sensors comprise an accelerometer and the environmental conditions comprise acceleration.
20. (Previously Presented) The system of claim 16, the environmental conditions comprising one or more of impact and temperature.
21. (Previously Presented) The system of claim 16, the environmental conditions comprising free fall to determine a drop distance of the product.
22. (Previously Presented) The system of claim 16, the environmental conditions comprising one or more acceleration events.
23. (Previously Presented) The system of claim 16, the environmental conditions comprising a preset temperature.
24. (Previously Presented) The system of claim 16, the sensors reporting the data as events with time stamp.
25. (Previously Presented) The system of claim 24, the sensors comprising a real time clock to provide time for the time stamp.
26. (Previously Presented) The system of claim 16, further comprising a plurality of interrogating devices to capture the conditions during shipment and after shipment.

27. (Previously Presented and Currently Amended) The method of claim 10, wherein the step of attaching comprises attaching a plurality of identical smart sensors to different locations on the product, each of the sensors configured to detect like environmental conditions.
28. (Previously Presented and Currently Amended) The method of claim 10, the step of monitoring environmental conditions comprising monitoring acceleration.
29. (Previously Presented and Currently Amended) The method of claim 10, further comprising the steps of storing and time-tagging event occurrences that exceed performance specifications of the product.
30. (Previously Presented and Currently Amended) The method of claim 10, the step of attaching comprising attaching a plurality of accelerometers to the product, wherein the environmental conditions comprise impact of the product.
31. (Previously Presented and Currently Amended) The method of claim 10, the step of attaching comprising sticking the sensors onto the product.